

100V N-Channel Enhancement Mode MOSFET

Description

The NP36N10 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS} = 100V \quad I_D = 36A$
 $R_{DS(ON)}(\text{Typ.}) = 32m\Omega \quad @ V_{GS}=10V$
 $R_{DS(ON)}(\text{Typ.}) = 38m\Omega \quad @ V_{GS}=4.5V$
- ◆ High density cell design for ultra low $R_{DS(on)}$
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high E_{AS}
- ◆ Excellent package for good heat dissipation
- ◆ Special process technology for high ESD capability

Application

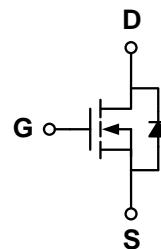
- ◆ Automotive applications
- ◆ Hard switched and high frequency circuits
- ◆ Uninterruptible power supply

Package

100% UIS TESTED!
100% ΔV_{ds} TESTED!

- ◆ TO-252-2L

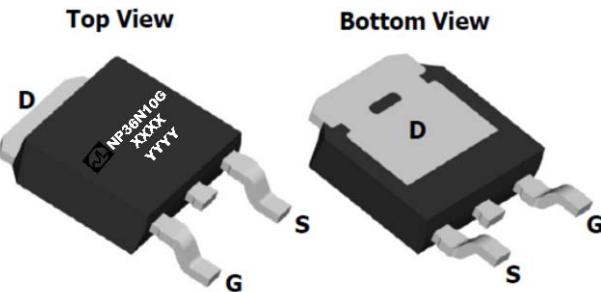
Schematic diagram



Marking and pin assignment

TO-252-2L

(Top View)



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP36N10G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	36	A
		26	
Pulsed Drain Current	I_{DP}	144	A
Avalanche energy(L=0.5mH)	E_{AS}	55	mJ
Maximum power dissipation	P_D	50	W
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	100	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V, GS=0V	T _J =25°C	-	-	1
			T _J =85°C	-	-	30
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.6	2.5	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =30A	-	32	42	mΩ
		V _{GS} =4.5V, I _D =10A	-	38	48	
On Status Drain Current	I _{D(ON)}	V _{DS} =100V, V _{GS} =10V	36	-	-	A
Diode Characteristics						
Diode Continuous Forward Current	I _S		-	-	36	A
Reverse Recovery Time	t _{rr}	I _F =10A, dI/dt=500A/us	-	32	-	ns
Reverse Recovery Charge	Q _{rr}		-	200	-	nC
Dynamic Characteristics²						
Input capacitance	C _{ISS}	V _{GS} =0V ,V _{DS} =50V f=1.0MHz	-	1630	-	pF
Output capacitance	C _{OSS}		-	100	-	
Reverse transfer capacitance	C _{RSS}		-	50	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =10V, V _{DS} =50V, R _L =5Ω , R _{GEN} =3Ω	-	7	-	ns
Turn-on Rise time	tr		-	7	-	
Turn-off delay time	t _{D(OFF)}		-	29	-	
Turn-off Fall time	tf		-	7	-	
Total gate charge	Q _g	V _{GS} =10V,I _D =10A V _{DS} =50V	-	34		nC
Gate-source charge	Q _{gs}		-	6		
Gate-drain charge	Q _{gd}		-	9	-	
Drain-Source Diode Characteristics						
Diode forward voltage	V _{SD}	I _{SD} =10A,V _{GS} =0V	-	0.8	1.1	V

Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

Typical Performance Characteristics

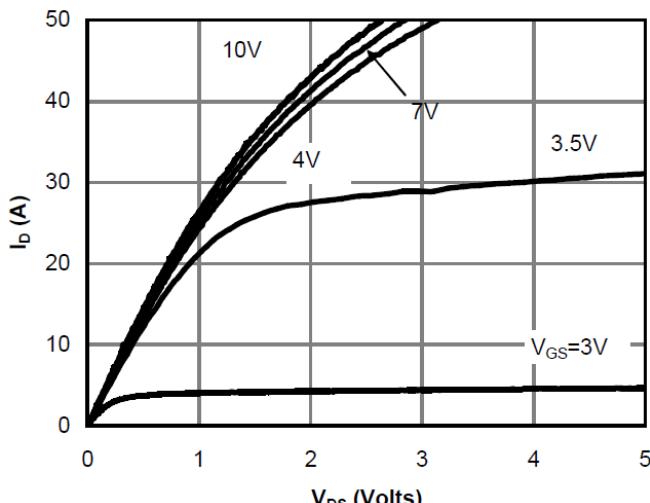


Fig 1: On-Region Characteristics

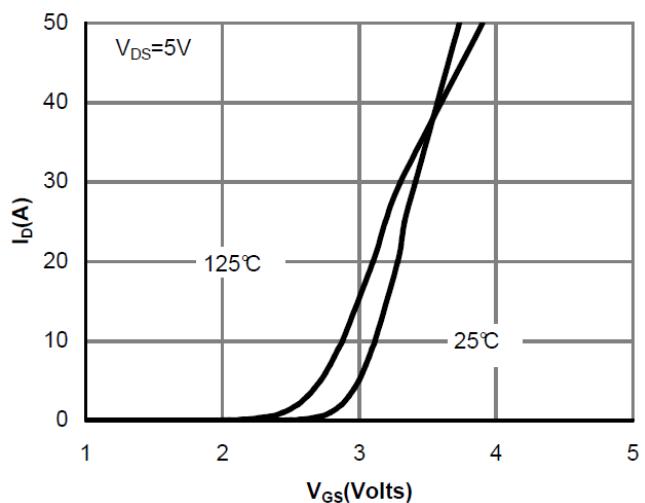


Figure 2: Transfer Characteristics

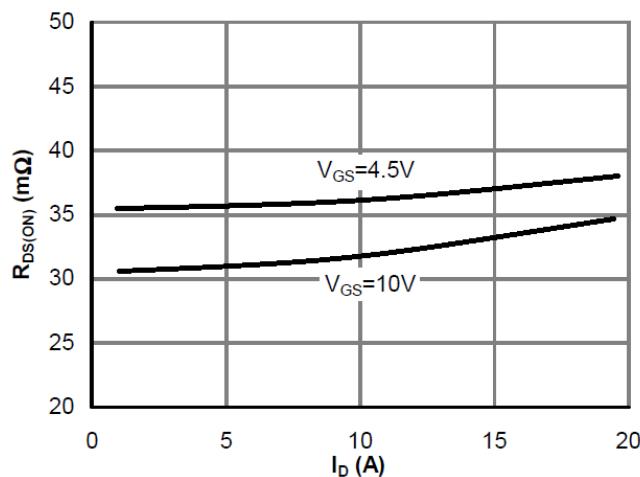


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

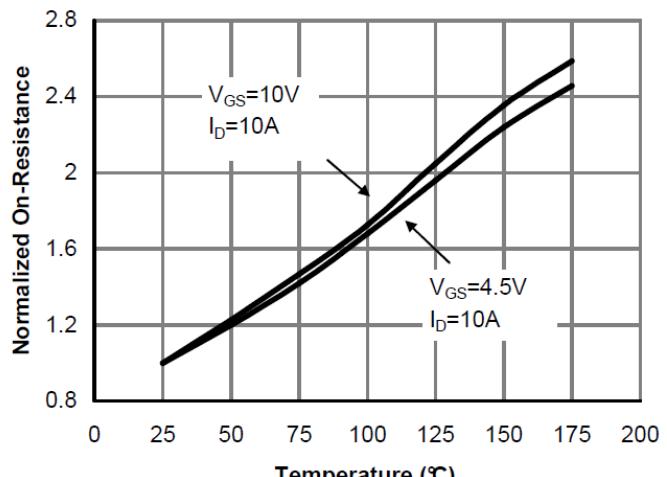


Figure 4: On-Resistance vs. Junction Temperature

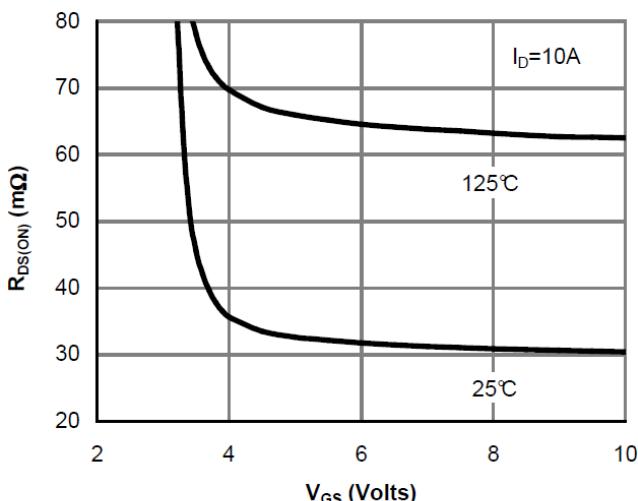


Figure 5: On-Resistance vs. Gate-Source Voltage

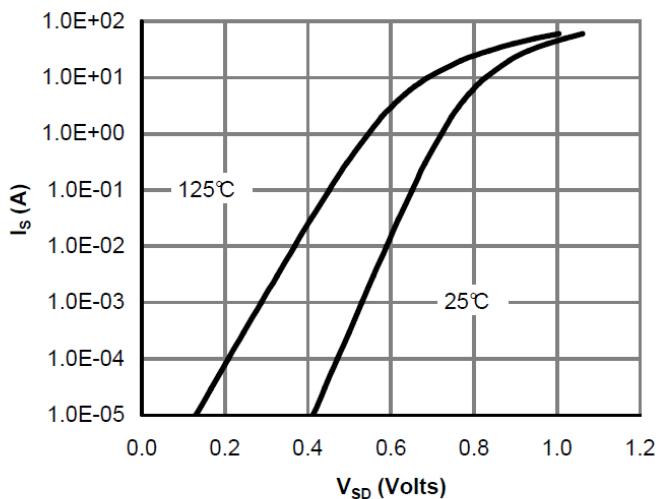


Figure 6: Body-Diode Characteristics

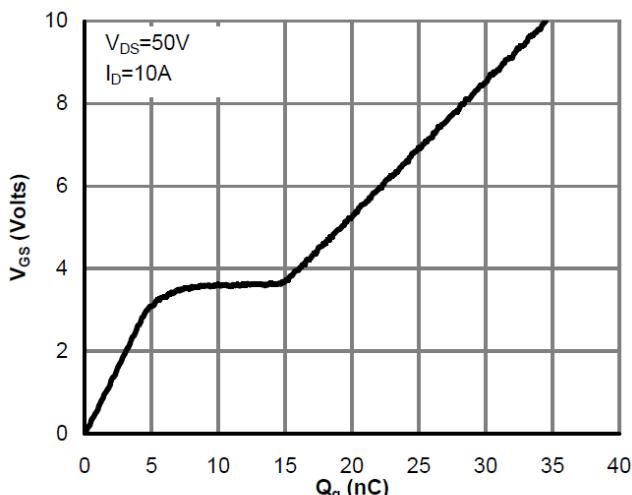


Figure 7: Gate-Charge Characteristics

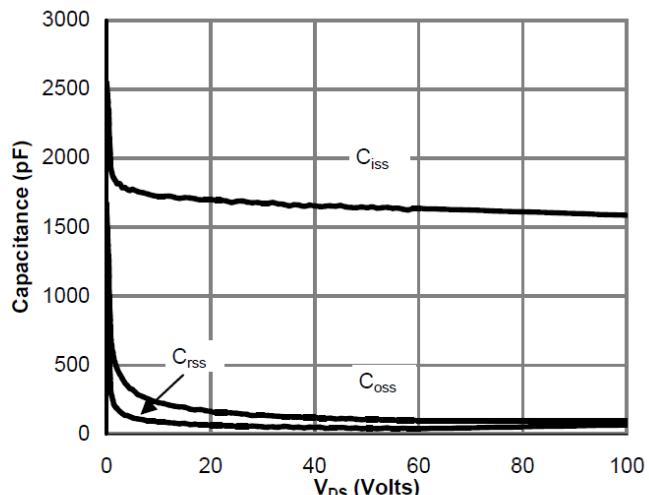


Figure 8: Capacitance Characteristics

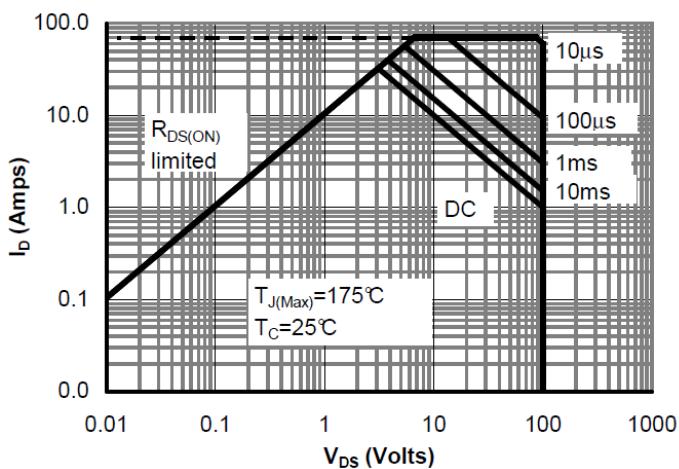


Figure 9: Maximum Forward Biased Safe Operating Area

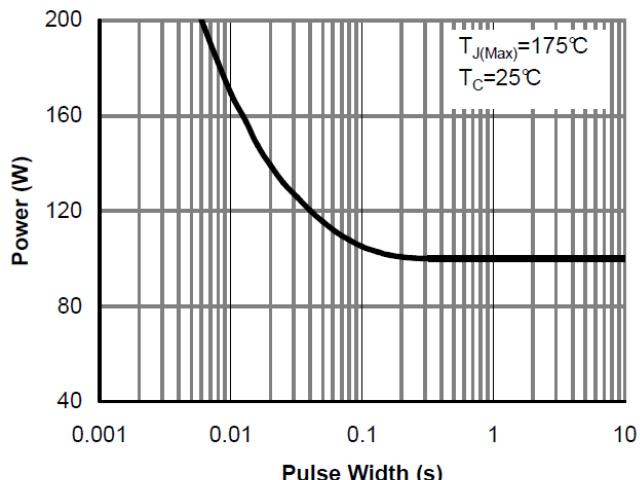


Figure 10: Single Pulse Power Rating Junction-to-Case

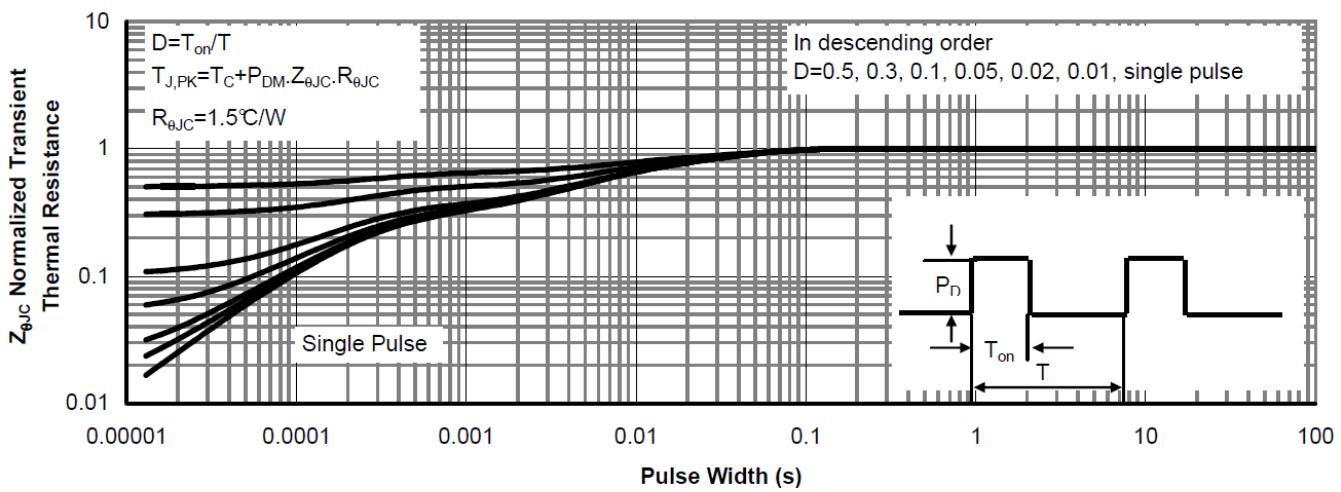


Figure 11: Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit & Waveforms

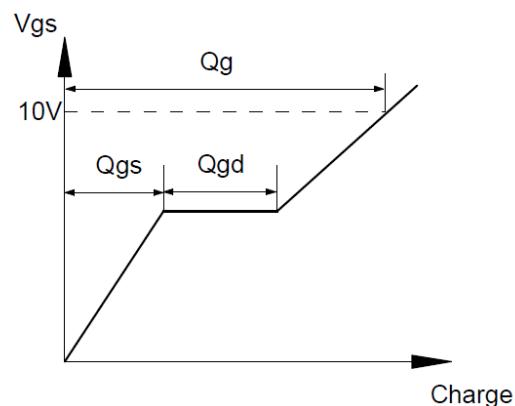
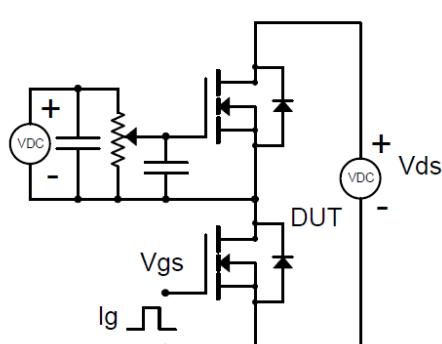


Figure B: Resistive Switching Test Circuit & Waveforms

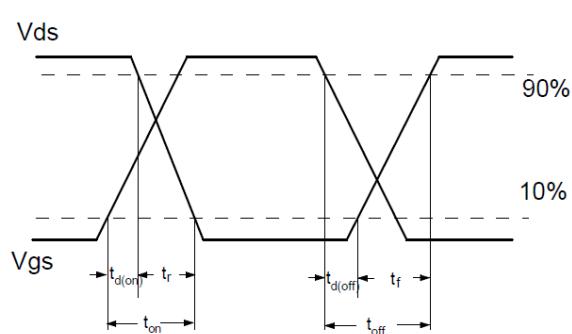
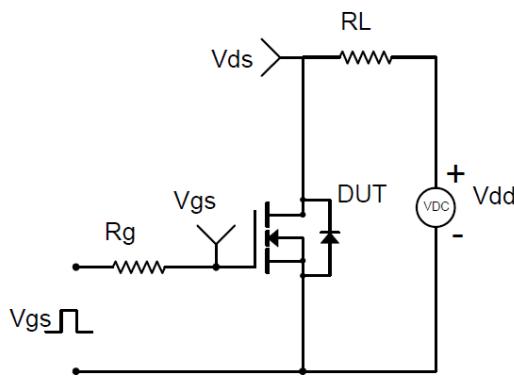


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

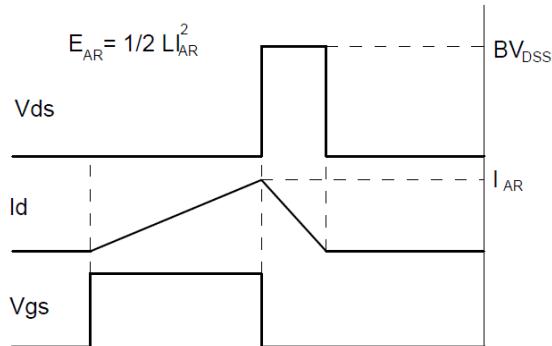
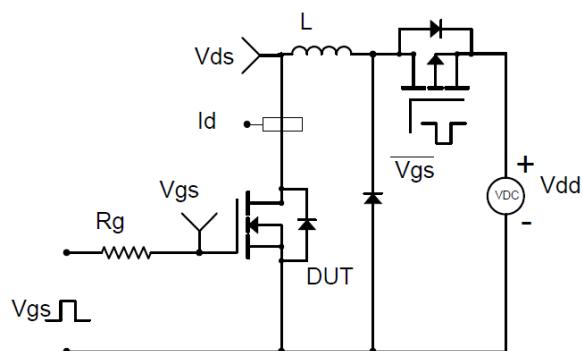
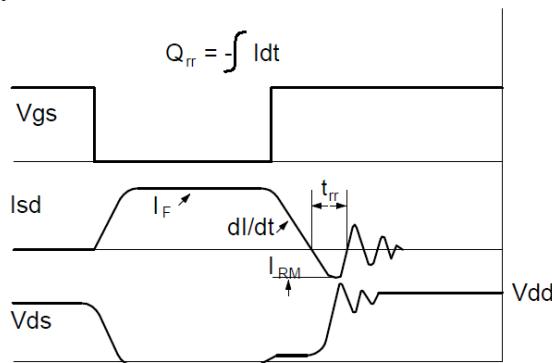
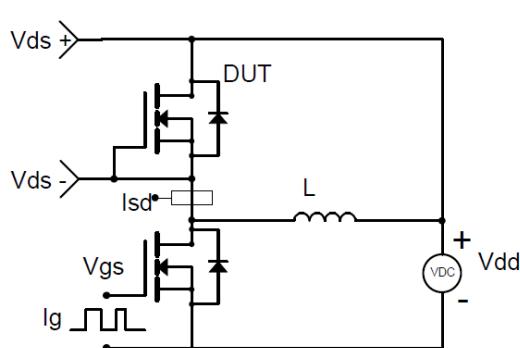
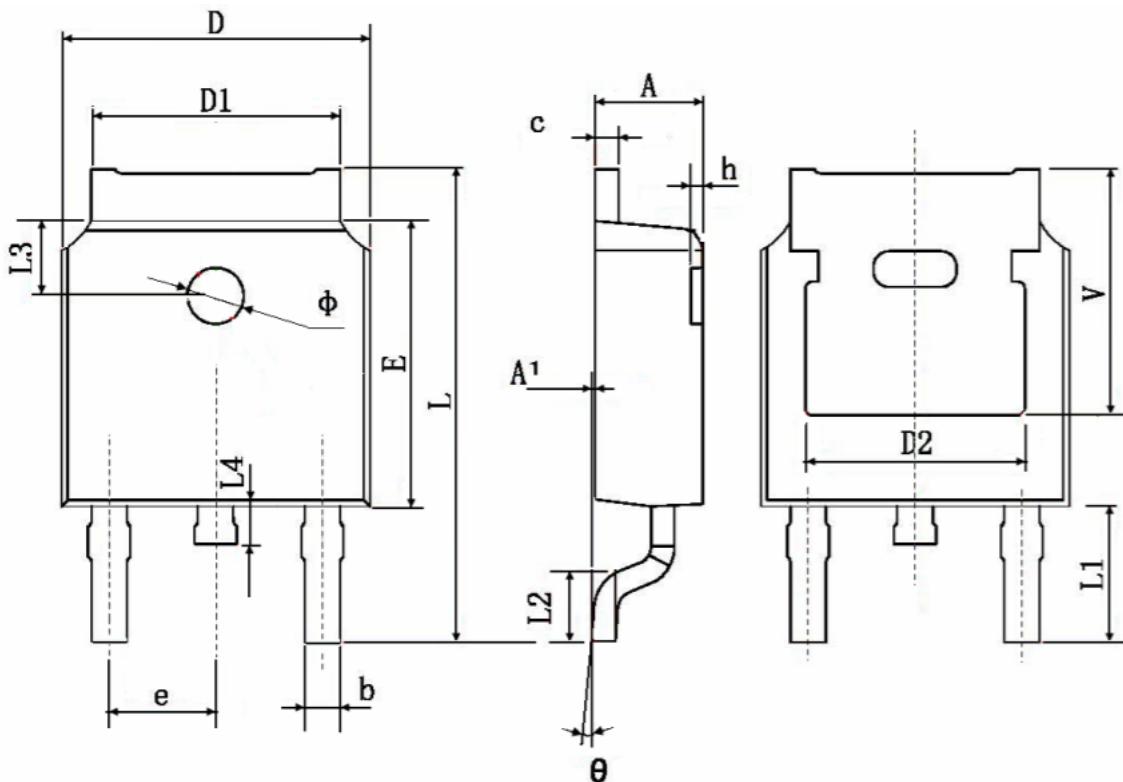


Figure D: Diode Recovery Test Circuit & Waveforms



Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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